

◆ Feature

- 1.Lowest height in this package footprint.
- 2.Shielded Molding construction.
- 3.Handles high transient current spikes without saturation.
- 4.Lowest DCR/ μ H, in this package size.
- 5.Ultra low buzz noise, due to composite construction.
- 6.Lead Free and RoHS compliant.



◆ Application

- 1.DC/DC converters in distributed power systems.
- 2.DC/DC converter for Field Programmable Gate Array (FPGA).
- 3.Notebook/Desktop/Server/CPU applications.

◆ How to Order

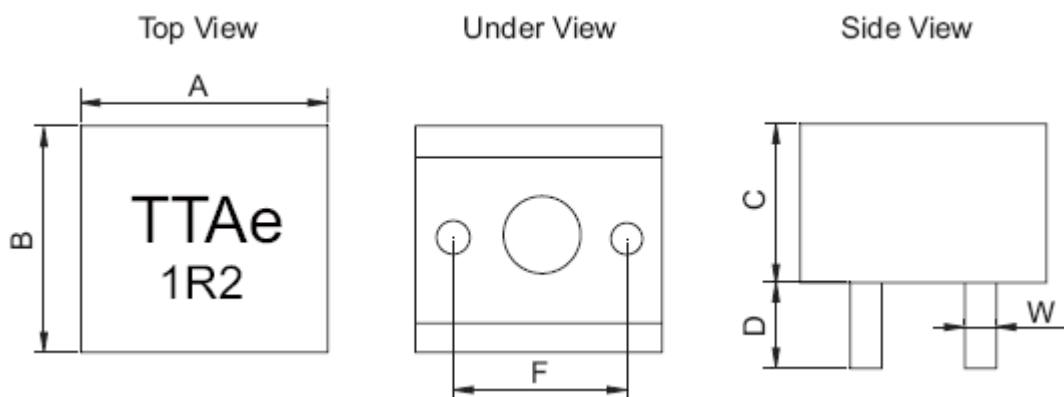
DMP **0808** **HBA** **1R2** **M** **V01**
 (1) (2) (3) (4) (5) (6)

- (1) Series
- (2) Dimension
- (3) Type: Material Code
- (4) Inductance: 1R2=1.20 μ H
- (5) Inductance Tolerance: M= \pm 20%
- (6) Control S/N

◆ Dimension

Unit: mm

DMP0808HBA Series	A	B	C	D	F	W
1R2	8.0MAX.	8.0MAX.	8.0MAX.	3.4 \pm 0.5	5.0 \pm 0.5	0.8 \pm 0.1
1R6						0.7 \pm 0.1



◆ Specification

Part Number	Inductance L0(uH) ±20%@ 0 A	I rms (A) Max.	I sat (A) Max.	DCR (mΩ) ±8%	Q (Min)
DMP0808HBA-1R2-M-V01	1.2	15	20	2.7	20
DMP0808HBA-1R6-M-V01	1.6	15	18	3.4	20

◆ Package

Size(mm)	0808	1010	1110	1210
Series	DMP0808HBAA	DMP1009HHAA	DMP1109HJAA	DMP1209HLAA
	DMP0808HBA	DMP1009HHA	DMP1109HJA	DMP1209HLA
Package(PCS)				
Size(mm)	0808	1010	1110	1210
Chip / Reel	162	120	108	102
Inner Box	1134	840	756	612
Carton	2268	1680	1512	1224